



Curiosity & Collaboration:

**Innovating Together for the Sustainable Progress of the
Semiconductor Industry**

Dr. Stephan Haferl, CEO Comet



The world has become...

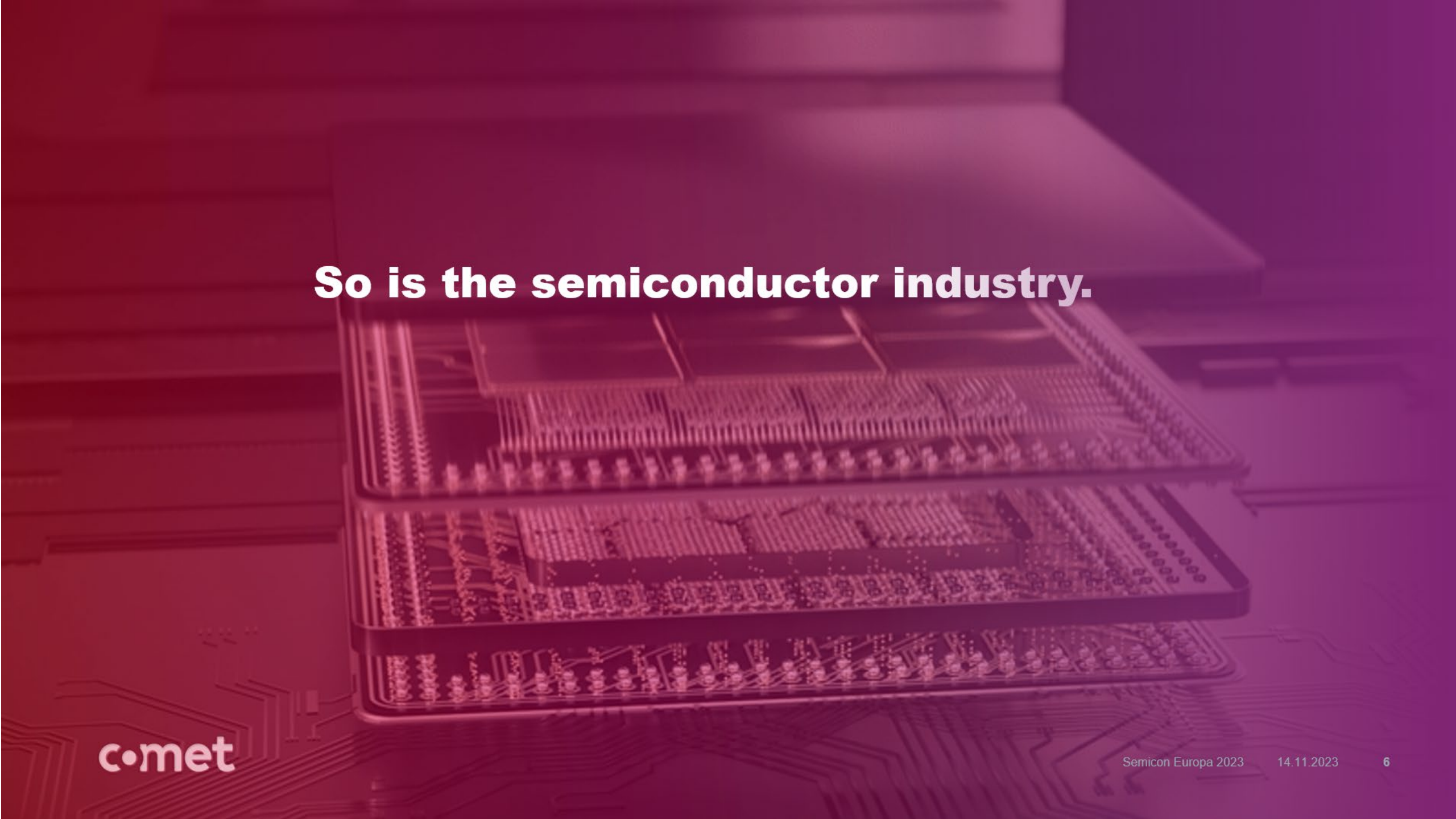


more complex.

faster.



interconnected.



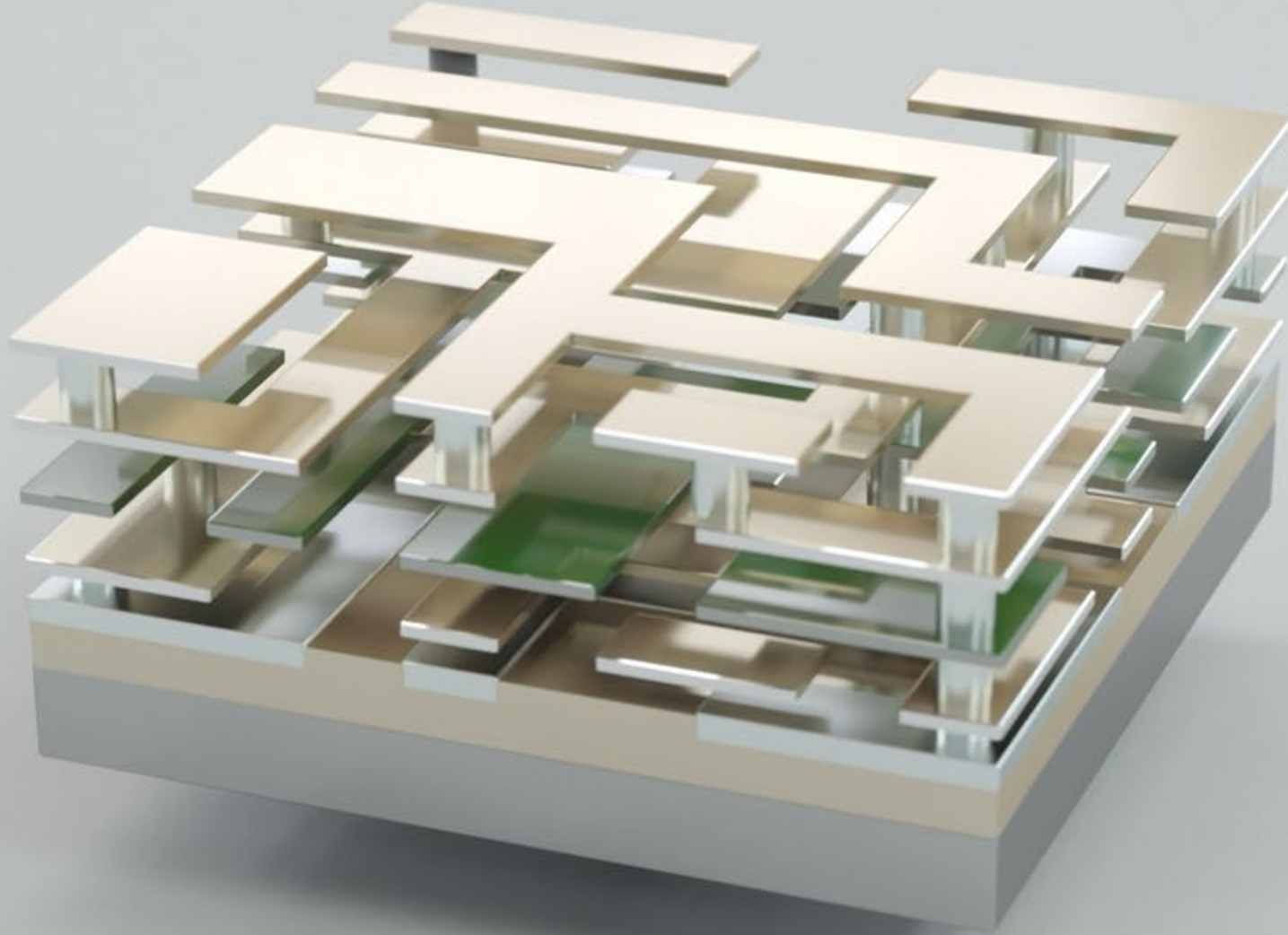
So is the semiconductor industry.

**How can we sustainably ensure
the quality and reliability of ever
smaller and more complex
semiconductor components?**

1

With curiosity

To innovate in the manufacture of advanced 3D structures.





Micro-second synchronization

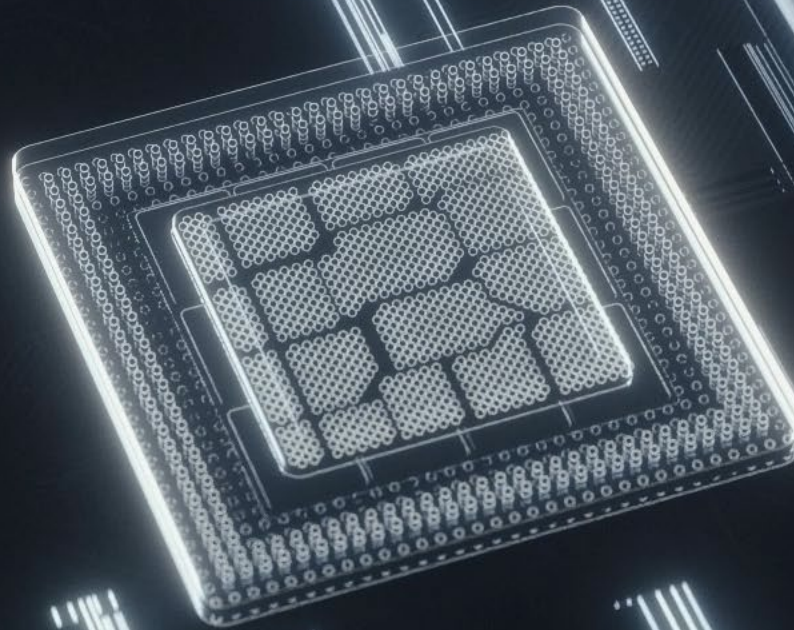
Synertia®



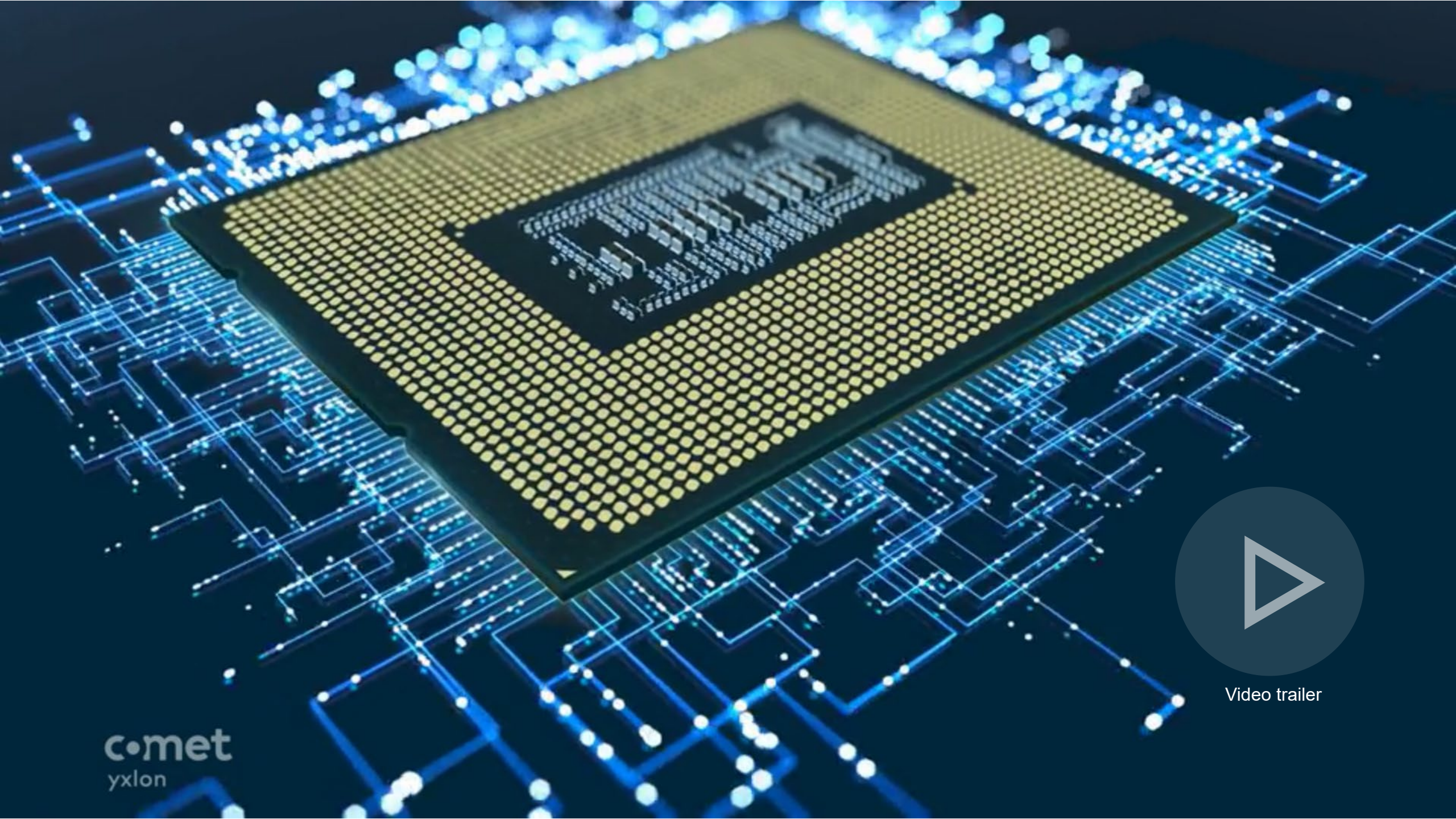
Making the next generation possible

c•met

Creating new inspection strategies.



c•met

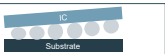
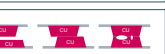
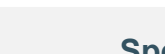


Video trailer

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yxlon

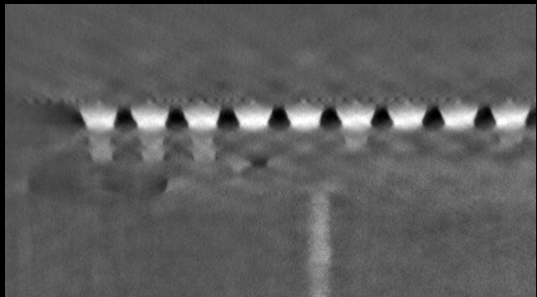
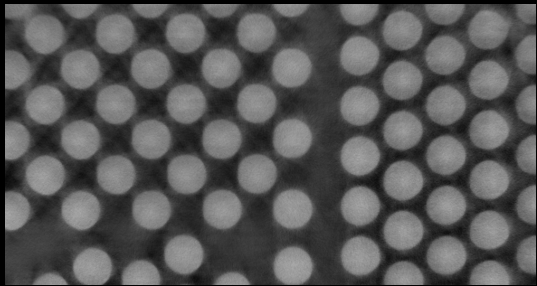
Hall B2
booth #454
November 14, 3pm

Next generation 3D X-Ray inspection provides fast & easy insights to critical defects

Specimen: Advanced Packages		Tools for inspection / failure analysis			
		Optical	X-Ray		FIB-SEM
			2D	Next Gen 3D	
Tilt		✓	✓	✓	✓
Missing bump		✓	✓	✓	✓
Bridge		✓	✓	✓	✓
Bulge/big-bump		✓	✓	✓	✓
Small bump / non-wet			✓	✓	✓
Shift			✓	✓	✓
Void			✓	✓	✓
Missing/ Small via connect				✓	✓
Head in pillow				✓	✓
Substrate cracks				✓	✓
Copper bonding issues				?	✓
		Speed   Detail recognition			

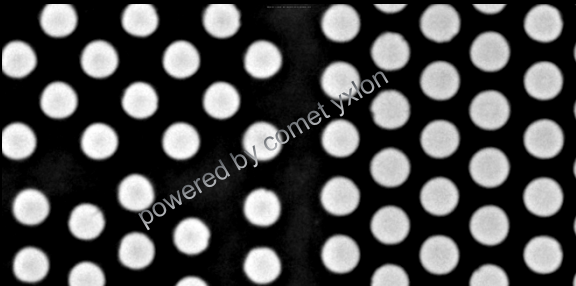
C4 bump | Real-time high-resolution insights in less than 5 minutes

Market Standard

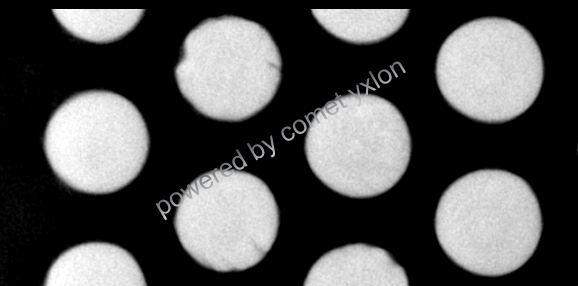


20 min scan

Next Generation 3D X-Ray image capabilities for Advanced Packaging



Less than 5 min scan



Less than 250 min scan

Curious? Join the team to know more



Dionys van de Ven
President
Comet Yxlon



Isabella Drolz
VP Product Marketing
Comet Yxlon



Christian Driller
VP R&D
Comet Yxlon

**Smart 3D X-ray
inspection driving
productivity**

**15.11.2023
11:40 AM**

 **Executive Forum**
Hall B2

**The Future of
Advanced Packaging
inspection is X-Ray**

**15.11.2023
04:15 PM**

Fab Management Forum
ICM (Internationales Congress
Center München)

**3D X-Ray inspection — Game
changer for Advanced Packaging**

**15.11.2023
12:25 PM**

 **Advanced Packaging Conference**
ICM (Internationales Congress Center
München)

**Zero defects matter | The power of
X-ray in Advanced Packaging**

**15.11.2023
11:00 AM**

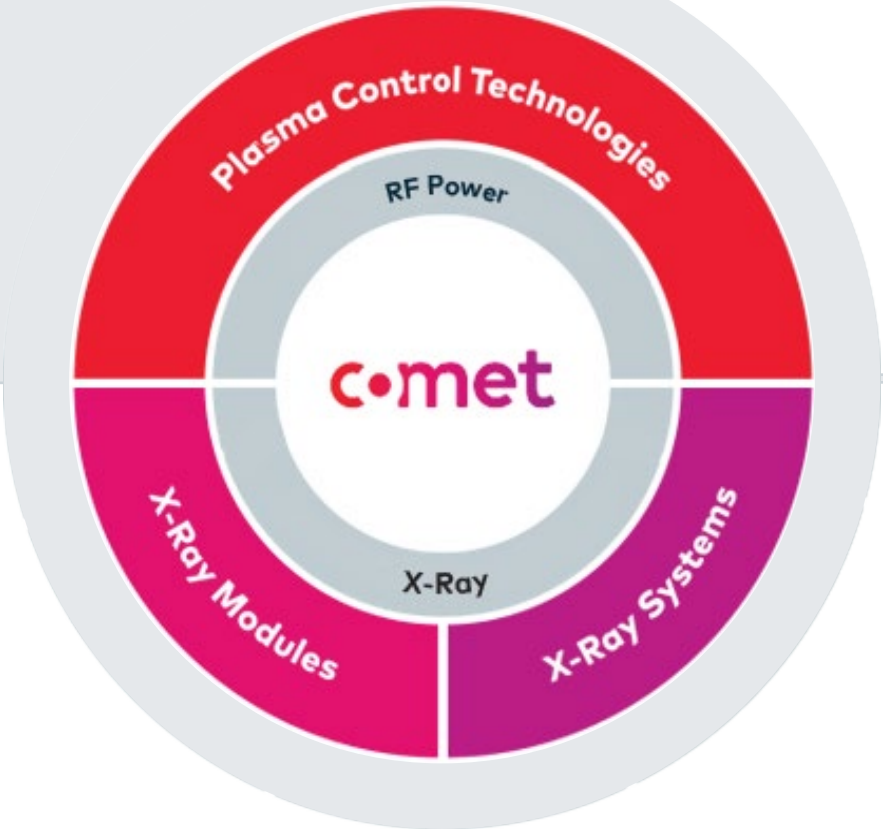
 **Future Disruptions**
TechARENA, Hall B1

But how did we get there?

2

With collaboration

Creating synergies



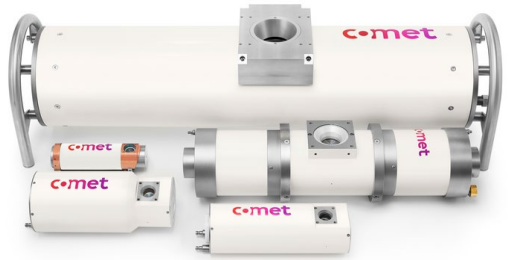
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pct

High-End RF Power
delivery systems for
plasma applications



High-End X-Ray
components and modules
for industrial applications

c•met
x-ray



c•met
yxlion

High-End X-Ray systems
for industrial environment
from R&D to production



Living our values.



**Customer
Orientation**



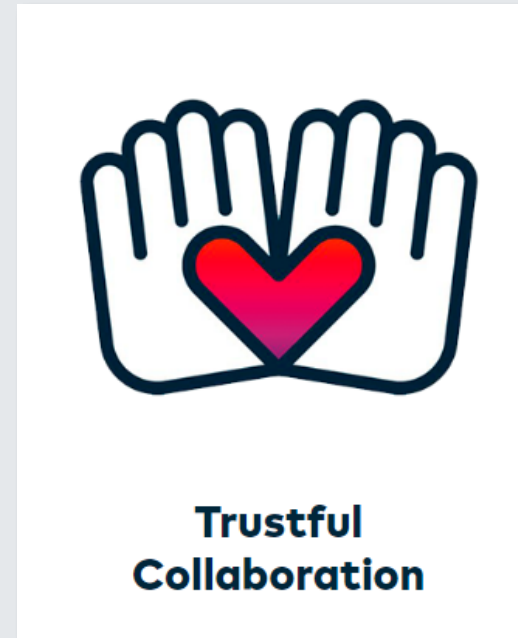
**Challenge and
Empower**



**Trustful
Collaboration**

We believe in collaboration is key for a sustainable development of the industry.

- **Bring the brightest people together, to collaborate in an unbiased way**
- **Crossing knowledge**
- **Creating a tunnel through complexity**
 - With colleagues
 - With customers
 - With peers
 - AND even with competition



Innovating for sustainable progress.

Because we firmly believe that innovation, in a world with finite resources, improves all our lives.

Led by experience. Driven by curiosity.

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